



Product Change Notification: MAAN-05ZIWF293

Date:

13-Aug-2026

Product Category:

8-Bit Microcontrollers, Memory

Notification Subject:

CCB 8431 Initial Notice: Qualification of MMT as an additional assembly site for selected 24AA0xx, 24AA014x, 24AA024x, 24AA025, 24AA025Exx, 24AA025UID, 25LC080D, 24AA16, 24AA16H, 24FC0xx, 24FC16, 24FC16H, 24LC014x, 24LC024x, 24LC025, 24LC01Bx, 24LC02Bx, 24LC04Bx, 24LC08Bx, 24LC16Bx, 25AA080x, 25AA128, 25AA160x, 25AA256, 25AA320A, 25AA640A, 25CS160, 25CS320, 25CS640, 25LC080Cx, 25LC128, 25LC160x, 25LC256, 25LC320A, 25LC640A, 93AA76x, 93AA86x, 93C76x, 93C86x, 93LC76x, 93LC86x, AT24C01x, AT24C02x, AT24C04x, AT24C08x, AT24C16x, AT24CM02, AT25080B, AT25160B, AT93C86A, ATtiny13x and ATtiny25 device families available in 8L SOIC (.150in) package.

Affected CPNs:

[MAAN-05ZIWF293_Affected_CPN_08132026.pdf](#)

[MAAN-05ZIWF293_Affected_CPN_08132026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for selected 24AA0xx, 24AA014x, 24AA024x, 24AA025, 24AA025Exx, 24AA025UID, 25LC080D, 24AA16, 24AA16H, 24FC0xx, 24FC16, 24FC16H, 24LC014x, 24LC024x, 24LC025, 24LC01Bx, 24LC02Bx, 24LC04Bx, 24LC08Bx, 24LC16Bx, 25AA080x, 25AA128, 25AA160x, 25AA256, 25AA320A, 25AA640A, 25CS160, 25CS320, 25CS640, 25LC080Cx, 25LC128, 25LC160x, 25LC256, 25LC320A, 25LC640A, 93AA76x, 93AA86x, 93C76x, 93C86x, 93LC76x, 93LC86x, AT24C01x, AT24C02x, AT24C04x, AT24C08x, AT24C16x, AT24CM02, AT25080B, AT25160B, AT93C86A, ATtiny13x and ATtiny25 device families available in 8L SOIC (.150in) package.

Pre and Post Summary Changes:

Final PCN Issue Date								X		
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Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: August 13, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_MAAN-05ZIWF293_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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QUALIFICATION PLAN SUMMARY

PCN #: MAAN-05ZIWF293

Date:

July 31, 2026

**Qualification of MMT as an additional assembly site for selected
24AA0xx, 24AA014x, 24AA024x, 24AA025, 24AA025Exx,
24AA025UID, 25LC080D, 24AA16, 24AA16H, 24FC0xx, 24FC16,
24FC16H, 24LC014x, 24LC024x, 24LC025, 24LC01Bx, 24LC02Bx,
24LC04Bx, 24LC08Bx, 24LC16Bx, 25AA080x, 25AA128, 25AA160x,
25AA256, 25AA320A, 25AA640A, 25CS160, 25CS320, 25CS640,
25LC080Cx, 25LC128, 25LC160x, 25LC256, 25LC320A, 25LC640A,
93AA76x, 93AA86x, 93C76x, 93C86x, 93LC76x, 93LC86x,
AT24C01x, AT24C02x, AT24C04x, AT24C08x, AT24C16x,
AT24CM02, AT25080B, AT25160B, AT93C86A, ATtiny13x and
ATtiny25 device families available in 8L SOIC (.150in) package.**

Purpose: Qualification of MMT as an additional assembly site for selected 24AA0xx, 24AA014x, 24AA024x, 24AA025, 24AA025Exx, 24AA025UID, 25LC080D, 24AA16, 24AA16H, 24FC0xx, 24FC16, 24FC16H, 24LC014x, 24LC024x, 24LC025, 24LC01Bx, 24LC02Bx, 24LC04Bx, 24LC08Bx, 24LC16Bx, 25AA080x, 25AA128, 25AA160x, 25AA256, 25AA320A, 25AA640A, 25CS160, 25CS320, 25CS640, 25LC080Cx, 25LC128, 25LC160x, 25LC256, 25LC320A, 25LC640A, 93AA76x, 93AA86x, 93C76x, 93C86x, 93LC76x, 93LC86x, AT24C01x, AT24C02x, AT24C04x, AT24C08x, AT24C16x, AT24CM02, AT25080B, AT25160B, AT93C86A, ATtiny13x and ATtiny25 device families available in 8L SOIC (.150in) package.

CCB No.: 8431

<u>Misc.</u>	Assembly site	MMT
	BD Number	BD-004605/01
	MP Code (MPC)	358A24C2XA00
	Part Number (CPN)	25LC256-E/SN
	MSL information	MSL-1
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	100
	Reliability Site	MTAI
<u>Lead-Frame</u>	Paddle size	90 x 90
	Material	CDA194
	Manufacturer	AAMI
	DAP Surface Prep	Cu-RT
	Treatment	Roughened
	Process	Stamped
	Lead-lock	Yes
	Part Number	10100812, 10100841, 10100866
	Lead Plating	Matte Tin
<u>Bond Wire</u>	Material	CuPdAu
<u>Die Attach</u>	Part Number	CRM-1064L (PFAS free)
	Conductive	Yes
<u>MC</u>	Part Number	G630AY
<u>PKG</u>	Package Type	SOIC
	Pin/Ball Count	8
	PKG width/size	150 mils

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Standard Pb-free Solderability	J-STD-002E : Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	30 bonds from a min. 5 devices.
Wire Sweep								Required for any reduction in wire bond thickness.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	JESD22-A103. +175°C for 504 hours or +150°C for 1008 hrs. Electrical test pre and post stress at +25°C and hot temp. Note: Prefer to use 150°C HTSL temperature for Cu wire qual; The 175°C temperature is acceptable as a parallel back-up test to avoid extending qual cycle time.	45	5	3	150	0	10	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. (MSL1/260)	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at +25°C and hot temp.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.